

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Seok Jae JEONG</td> <td>02/21/2012</td> </tr> <tr> <td>Young Kyu KIM</td> <td>02/21/2012</td> </tr> <tr> <td>Ju Hyun KIM</td> <td>02/21/2012</td> </tr> </tbody> </table>		Name	Execution Date	Seok Jae JEONG	02/21/2012	Young Kyu KIM	02/21/2012	Ju Hyun KIM	02/21/2012
Name	Execution Date								
Seok Jae JEONG	02/21/2012								
Young Kyu KIM	02/21/2012								
Ju Hyun KIM	02/21/2012								
RECEIVING PARTY DATA									
Name:	LG Electronics Inc.								
Street Address:	20, Yeouido-dong, Youngdungpo-gu								
City:	Seoul								
State/Country:	REPUBLIC OF KOREA								
Postal Code:	150-721								
PROPERTY NUMBERS Total: 1									
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13392174</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13392174				
Property Type	Number								
Application Number:	13392174								
CORRESPONDENCE DATA									
Fax Number:	(703)766-3644								
Phone:	7037663777								
Email:	Assigned@ked-iplaw.com								
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>									
Correspondent Name:	KED & ASSOCIATES, LLP								
Address Line 1:	P.O. Box 8638								
Address Line 4:	Reston, VIRGINIA 20195								
ATTORNEY DOCKET NUMBER:	K-1387								
NAME OF SUBMITTER:	Daniel Y.J. Kim								
Total Attachments: 4 source=K-1387Assignment#page1.tif source=K-1387Assignment#page2.tif source=K-1387Assignment#page3.tif source=K-1387Assignment#page4.tif									

OP \$40.00 13392174

Docket No.:

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- (1) JEONG, Seok Jae
- (2) KIM, Young Kyu
- (3) KIM, Ju Hyun

who have made a certain new and useful invention, hereby sell, assign and transfer unto

LG ELECTRONICS INC.

20, Yeouido-dong, Youngdungpo-gu, Seoul, 150-721, Republic of Korea

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

METHOD FOR MANUFACTURING A MASTER MOLD WHICH IS USED TO FORM A MICROPATTERNED FILM APPLIED TO AN EXTERIOR OF A HOUSEHOLD APPLIANCE AND MANUFACTURING APPARATUS AND METHOD OF THE FILM USING THE MASTER MOLD

(a) for which an application for United States Letters Patent was filed on _____, and identified by United States Serial No. _____; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and/or that claim priority thereto and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof and/or that claim priority thereto, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

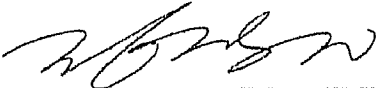
AND the undersigned hereby grants the firm of KED & ASSOCIATES, LLP the power to insert on this assignment any further identification that may be necessary or desirable in order to comply with the rules of any issuing authority, including the United States Patent and Trademark Office, for recordation of this document.

SIGNED on the dates indicated aside our signatures:

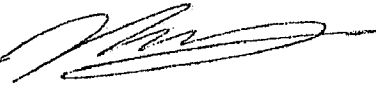
10FLSL050US02

INVENTORS

DATE SIGNED

1) 
Name: JEONG, Seok Jae

2012.02.21

2) 
Name: KIM, Young Kyu

2012.02.21

3) _____
Name: KIM, Ju Hyun

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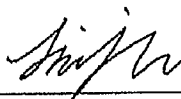
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Feb. 21. 2012

